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Packaging material for foodstuffs, etc. - comprises plastic film plasma treated in nitrogen (contg.) atmos. and metal vapour deposition layer formed using adhesive

Patent Assignee: TOPPAN PRINTING CO LTD (TOPP)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
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JP 63242534	A	19881007	JP 8777333	A	19870330	198846 B
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Priority Applications (No Type Date): JP 8777333 A 19870330

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
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JP 63242534	A	3		
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Abstract (Basic): JP 63242534 A

The packaging material is composed of a plastic film having its surface low temp. plasma treated in an atmos. of nitrogen gas or a mixed gas contg. nitrogen gas, and a metal vapour deposition layer formed on the plasma-treated surface of the film through an adhesive. The plastic film is pref. formed of a polyamide resin or a polyethylene terephthalate resin.

USE/ADVANTAGE - For packaging of foodstuffs, etc. This material is laminated to a heat adhesive film of PE, PP, etc. to form a retort-sterilisation packaging material. The low temp. plasma treatment provides a high delamination resistance even after retort sterilisation.

In an example, A 15 microns thick nylon film was low temp. plasma treated. The film was laminated to a 70 microns thick non-oriented PP film through an adhesive. (The delamination strength before retorting 400 g/15 mm, that after retorting 400 g/15 mm).

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